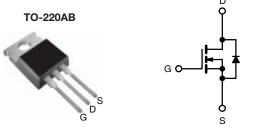
HALOGEN

FREE



## **D Series Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	450			
R <sub>DS(on)</sub> max. (Ω) at 25 °C	V <sub>GS</sub> = 10 V 0.6			
Q <sub>g</sub> max. (nC)	30			
Q <sub>gs</sub> (nC)	4			
Q <sub>gd</sub> (nC)	7			
Configuration	Single			



N-Channel MOSFET

#### **FEATURES**

- Optimal design
  - Low area specific on-resistance
  - Low input capacitance (Ciss)
  - Reduced capacitive switching losses
  - High body diode ruggedness
  - Avalanche energy rated (UIS)
- · Optimal efficiency and operation
  - Low cost
  - Simple gate drive circuitry
  - Low figure-of-merit (FOM): Ron x Qg
  - Fast switching
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

#### APPLICATIONS

- Consumer electronics
  - Displays (LCD or plasma TV)
- Server and telecom power supplies
  - SMPS
- Industrial
  - Welding
  - Induction heating
  - Motor drives
- Battery chargers

ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free	SiHP10N40D-E3			
Lead (Pb)-free and Halogen-free	SiHP10N40D-GE3			

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	$V_{DS}$	400			
Gate-Source Voltage	V <sub>GS</sub>	± 30	V		
Gate-Source Voltage AC (f > 1 Hz)		30			
Continuous Drain Current (T <sub>J</sub> = 150 °C)	$V_{GS}$ at 10 V $T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 100 ^{\circ}\text{C}$	1	10	A	
	$V_{GS}$ at 10 $V_{C}$ $T_{C} = 100 ^{\circ}C$	I <sub>D</sub>	6		
Pulsed Drain Current <sup>a</sup>	I <sub>DM</sub>	23			
Linear Derating Factor		1.2	W/°C		
Single Pulse Avalanche Energy <sup>b</sup>	E <sub>AS</sub>	194	mJ		
Maximum Power Dissipation	$P_{D}$	147	W		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C		
Drain-Source Voltage Slope	T <sub>J</sub> = 125 °C dV/dt		24	V/ns	
Reverse Diode dV/dt <sup>d</sup>	uv/ut	0.6	V/115		
Soldering Recommendations (Peak temperature) c for 10 s			300	°C	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 2.3 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 13 A.
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ , starting  $T_J = 25$  °C.



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	0.85	G/ VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static						•	
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		400	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I <sub>D</sub> = 250 μA	-	0.53	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3	-	5	V
Gate-Source Leakage	I <sub>GSS</sub>		V <sub>GS</sub> = ± 30 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V		-	1	μΑ
Zoro date voltage Brain Guirone	פטי	$V_{DS} = 320 \text{ V}$	$V_{\rm S} = 0 \ V_{\rm T} = 125 \ ^{\circ}{\rm C}$	-	-	10	μΑ
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}$	$I_D = 5 A$	-	0.5	0.6	Ω
Forward Transconductance	$g_{fs}$	V <sub>DS</sub>	$_{s} = 50 \text{ V}, I_{D} = 5 \text{ A}$	-	2.7	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>		$V_{GS} = 0 V$	-	526	-	
Output Capacitance	C <sub>oss</sub>		$V_{DS} = 100 \text{ V},$	-	59	-	
Reverse Transfer Capacitance	$C_{rss}$		f = 1 MHz	-	9	-	_
Effective Output Capacitance, Energy Related <sup>a</sup>	$C_{o(er)}$	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 0 V to 320 V		-	66	-	pF
Effective Output Capacitance, Time Related <sup>b</sup>	$C_{o(tr)}$			-	84	-	
Total Gate Charge	$Q_g$			-	15	30	
Gate-Source Charge	$Q_{gs}$	V <sub>GS</sub> = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 5 \text{ A}, V_{DS} = 320 \text{ V}$		4	-	nC
Gate-Drain Charge	Q <sub>gd</sub>			-	7	-	1
Turn-On Delay Time	t <sub>d(on)</sub>			-	12	24	
Rise Time	t <sub>r</sub>	V <sub>DD</sub> =	$V_{DD} = 400 \text{ V}, I_D = 10 \text{ A}, V_{GS} = 10 \text{ V}, R_0 = 9.1 \Omega$		18	36	no
Turn-Off Delay Time	t <sub>d(off)</sub>				18	36	ns
Fall Time	t <sub>f</sub>			-	14	28	
Gate Input Resistance	R <sub>g</sub>	f = 1 MHz, open drain		0.9	1.8	3.6	Ω
<b>Drain-Source Body Diode Characteristic</b>	s	_					
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	10	
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	40	A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 5 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 5 A, dI/dt = 100 A/μs <sup>, V</sup> <sub>R</sub> = 25 V		-	230	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>			-	1.6	-	μC
Reverse Recovery Current	I <sub>RRM</sub>			_	14	-	Α

## Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

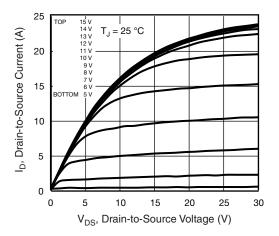


Fig. 1 - Typical Output Characteristics

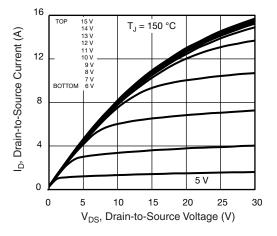


Fig. 2 - Typical Output Characteristics

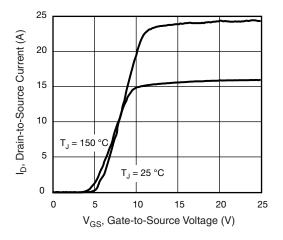


Fig. 3 - Typical Transfer Characteristics

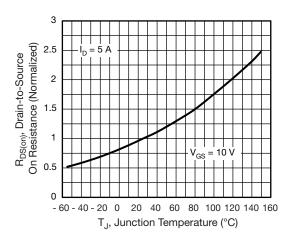


Fig. 4 - Normalized On-Resistance vs. Temperature

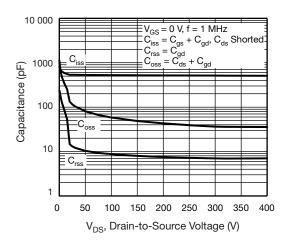


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

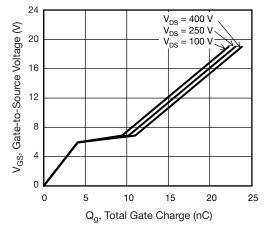


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



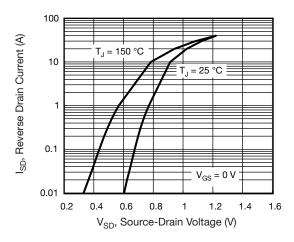


Fig. 7 - Typical Source-Drain Diode Forward Voltage

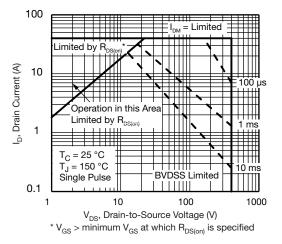


Fig. 8 - Maximum Safe Operating Area

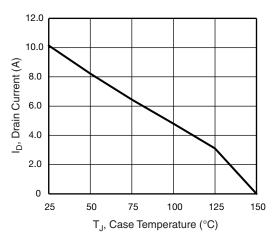


Fig. 9 - Maximum Drain Current vs. Case Temperature

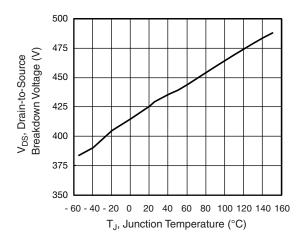


Fig. 10 - Temperature vs. Drain-to-Source Voltage

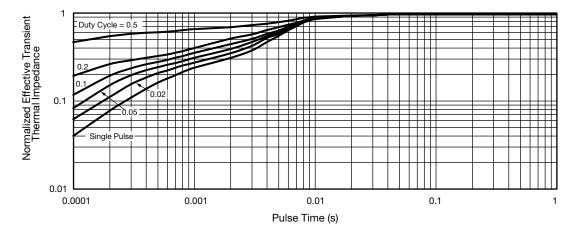


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



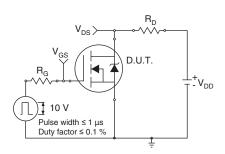


Fig. 12 - Switching Time Test Circuit

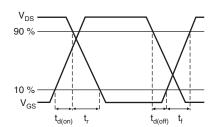


Fig. 13 - Switching Time Waveforms

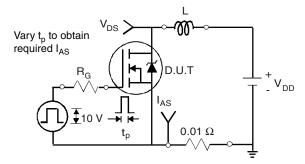


Fig. 14 - Unclamped Inductive Test Circuit

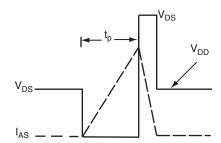


Fig. 15 - Unclamped Inductive Waveforms

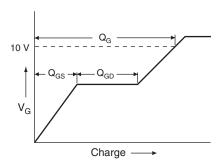


Fig. 16 - Basic Gate Charge Waveform

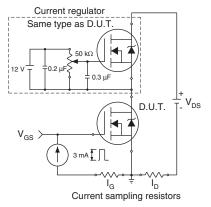
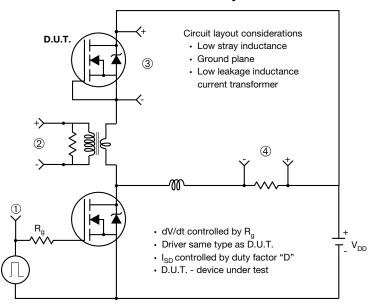


Fig. 17 - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



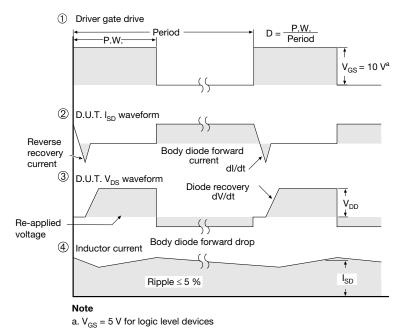


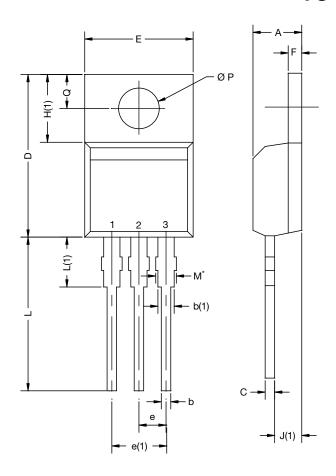
Fig. 18 - For N-Channel

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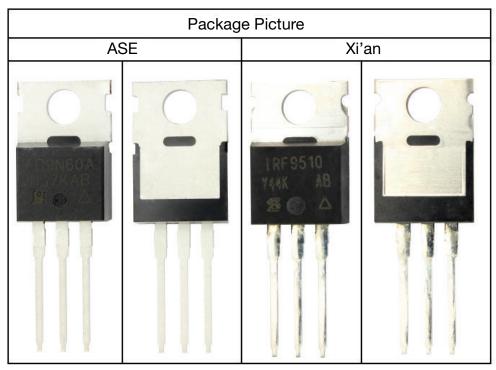
# TO-220-1



DIM	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
E	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

### Note

 $\bullet$   $M^{\star}=0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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